	PART NO.			REVISIONS								
multicomp			REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE		
	460DE08C3	-	A	RELEASED	Kiran	31/3/09	∕~Veena⊂	31/3/09	Famell	14/04/09		
MicroSD Card												
4.80 (Vacuum Placement Area) 2.90	1.75 ±0.20 Slide Shell Lock Position			0.70								
Connector Outline 0.80 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.76 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0.77 0												
	Recommended PCB L	ayout (Top \	/iew)									
	General Toler			N.III mantena a								
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	PART NO.		REVISIONS									
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		-	A	RELEASED	Kiran	31/3/09/	∕~Veeniå⊂S	31/3/09	Famell	14/04/09		

Material		
Insulator	: Liquid crystal polymer.	
Contacts	: Phosphor bronze.	
Shell	: Stainless steel (SUS301).	
Contact Plating		
Underplate	: 50μ inches to 100μ inches nickel.	
Contact area	: 1µ inches gold.	
Solder tails area	: 1µ inches gold.	
Electrical		
Maximum rate voltage	: 10V.	
Maximum current rating	: 0.5A.	
Contact resistance	: 80m $\Omega$ initial (final 100m $\Omega$ ).	
Minimum insulation resistance	: 1000MΩ at 500V dc.	
Dielectric withstanding voltage	: 500V ac/minute.	
Temperature range	: -25°C to +85°C.	
Mating cycles	: 10,000 insertions.	

## Pin Assignment Table

Pin Number	Name					
1	DAT2					
2	CD/DAT3					
3	CMD					
4	VDD					
5	CLK					
6	VSS					
7	DAT0					
8	DAT1					

## Part Number Table

Description	Part Number
Connector, Micro SD, Hinged	460DE08C3

http://www.farnell.com

http://www.newark.com

http://www.cpc.co.uk

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		CHECKED BY:	DATE:	SIZE	DWG NO.		ELECTRONIC FILE		REV
	DIMENSIONS ARE	Veena	31/03/09	Δ		M10002001		152-TDS DWG	Α
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